PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
BOK GYU MIN	12/17/2009
JAE MYUN KIM	12/17/2009
DA UN NAH	12/17/2009

RECEIVING PARTY DATA

Name:	HYNIX SEMICONDUCTOR INC.
Street Address:	SAN 136-1, AMI-RI, BUBAL-EUP, ICHEON-SI
City:	GYEONGGI-DO
State/Country:	REPUBLIC OF KOREA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12647657

CH $40.00 12647657

CORRESPONDENCE DATA

Fax Number: (312)427-6663
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 3124271300
Email: nicholas.kubacki@ladas.net
Correspondent Name: RICHARD J. STREIT
Address Line 1: LADAS & PARRY, 224 SOUTH MICHIGAN AVE.
Address Line 4: CHICAGO, ILLINOIS 60604

ATTORNEY DOCKET NUMBER:	CU-7995 WWP/NK
NAME OF SUBMITTER:	Woochoon W. Park

Total Attachments: 2
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UNITED STATES OF AMERICA

ASSIGNMENT

In consideration of the payment of ASSIGNEE to ASSIGNOR of the sum of One Dollar ($1.00), the receipt of which is hereby acknowledged, and for the other good and valuable consideration,

ASSIGNOR:
Name: Bok Gyu MIN
Address: 106-1005, Godam Dormitory, Godam-dong, Icheon-si, Gyeonggi-do, Korea
Name: Jae Myun KIM
Address: 435-602, Hyundai Home Town, Kkotmaemaeul, 1304, Jukjeon-dong, Suji-gu, Yongin-si, Gyeonggi-do, Korea
Name: Da Un NAH
Address: 207-403, Family Apts., Munjeong-dong, Songpa-gu, Seoul, Korea

(INVENTOR NAME AND ADDRESS)

hereby sells, assigns and transfers to

ASSIGNEE:
Name : Hynix Semiconductor Inc.
Address : San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do, Korea

(ASSIGNEE NAME AND ADDRESS)

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions in and to, any and all improvements which are disclosed in the invention entitled:

SEMICONDUCTOR PACKAGE AND STACKED SEMICONDUCTOR PACKAGE HAVING THE SAME

(TITLE)

and which is found in *(check one applicable item below)*

☑ U.S. patent application executed on even date herewith

☐ U.S. Application Serial No. ______________ filed on ______________

and, in and to all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, substitute, reissue or re-examination thereof.

ASSIGNOR hereby convenants that no assignment, sale agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

ASSIGNOR further convenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference or litigation related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/we have set our hand and seal

December 17, 2009	Bok Gyu MIN
Date	INVENTOR: Bok Gyu MIN
December 17, 2009	Jae Myun KIM
Date	INVENTOR: Jae Myun KIM
December 17, 2009	Da Un NAH
Date	INVENTOR: Da Un NAH